Applicab	le standai	<sup>.</sup> d								
1-1	1	Temperature Range	-55 to +85°C (Note1) Storage		e Temperature R	ange -10	0 °C to +60°C (	Note3	)	
Rating		Humidity Range		)% (Note2)		Humidity Rang		)% to 70% (I		
	Voltage		·		_	plicable Connector		DF58-*S-1.2C(##)		
	Current	Number of	AWG28 AWG30							
		contacts								
		2	3.0A	2.5A						
		3	2.5A	2.0A	_					
		4,6	2.0A	1.5A						
			9	Specifica	ations					
	Item		Test meth	nod			Requirements		QT	АТ
Construc	ction	<b>'</b>				II.			-1	
General E	kamination	Visually and by	Visually and by measuring instrument.				awing.		Х	Х
Marking			Confirmed visually.							
	Characteri					L			l	
Contact Re	esistance	20mV MAX, 1m	20mV MAX, 1mA (DC or 1000Hz).				10 mΩ MAX.			
Insulation	Resistance	100 V DC.	100 V DC.				100 MΩ MIN.			
Voltage Pr	oof	500 V AC for 1	500 V AC for 1 min.				No flashover or breakdown.			_
Mechani	cal Chara	cteristics								
Mechanical Operation 10 times inserti-			on and extraction.		1.Contact resistance: 20 m Ω MAX.			Х	_	
						Number of Mating Unmating				
Mating and unmating force		It takes out and	It takes out and inserts with a conformity connector.				Mating	Unmating	Х	_
							force 12.0N MAX	force 1.2N MIN	-	
						3	16.0N MAX	1.3N MIN	-	
						4	20.0N MAX	1.4N MIN		
						6	28.0N MAX	1.6N MIN		
		Frequency 10 to	Frequency 10 to 55 Hz, single amplitude 0.75 mm, at			1.No electrical discontinuity of 1 $\mu$ s.				_
		10 cycles for 3	10 cycles for 3 direction.				2.No damage, crack or looseness of parts.			
Shock		Acceleration 49	Acceleration 490 m/s <sup>2</sup> duration of pulse 11 ms at 3							_
		times for 3 direc								
Environr	nental Ch	aracteristics								
			± 2°C , humidity 90 to 95 %, 96 h.			1.Contact resistance: 20 m Ω MAX.				_
(Steady St	ate)	(After leaving th	(After leaving the room temperature for 1 to 2h.)				2.Insulation resistance: 100 M $\Omega$ MIN.			
Rapid Change Of			Temperature -55°C→ +85°C				3.No damage, crack or looseness of parts.			
Temperature										
		Under 5 Cycles	Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN)							
			(After leaving the room temperature for 1 to 2h.)							
Dry Heat		Exposed at		2010 101 1 10 2	··· <i>)</i>					
Cold		Exposed at	-55±3°C, 96h	<u> </u>		-				
Remarks										

## Remarks

Note 1: Include the temperature rising by current.

Note 2:No condensing

Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb board, operating temperature and humidity range is applied for interim storage during transportation.

	COUN	NT DESCRIPTION OF REVISIONS			DESIGNED		CHECKED	DATE		
$\sqrt{0}$										
						APPROVE	D HS. OKAWA	16. 06. 21		
						CHECKED	YN. TAKASHITA	16. 06. 20		
						DESIGNED	TH. YOSHIZAWA	16. 06. 20		
Unles	Unless otherwise specified, refer to IEC 60512.					DRAWN	TH. YOSHIZAWA	16. 06. 20		
Note	Note QT:Qualification Test AT:Assurance Test X:Applicable Test				t DRAWING	DRAWING NO.		ELC-371175-00-00		
HS.		SPECIFICATION SHEET			PART NO.		DF58-*P-1. 2V (21	)		
		HIROSE ELECTRIC CO., LTD.			CODE NO.		CL666-	1/2		

		Specifica	ations	3				
It	em	Test method			Requ	uirements	QT	АТ
	soldering heat	1) Reflow soldering  « Reflow area »  250°C MAX 10 sec MAX  220°C MIN 60 sec MAX  « Preheating area »  150°C to 180°C 90 sec to 120 sec  2) Manual soldering  Soldering iron temperature :350±10°C,  Soldering time : 3sec.  No strength on contact.			ormation of cas erminals.	e of excessive looseness	X	_
Solderability		Soldered at solder temperature, 245°c for insertion duration, 5sec.			shall cover a m	inimum of eing immersed.	Х	_
Note QT:Q	Note QT:Qualification Test AT:Assurance Test X:Applicable Test		DRAWING NO.		ELC-371175-	LC-371175-00-00		
HS.	SPECIFICATION SHEET			PART NO. DF:		F58-*P-1. 2V (21)		
• • •	HIROSE ELECTRIC CO., LTD.		CODE NO		(	CL666- 🛕 2		